

A ZERO CAPACITANCE BONDPAD UTILIZING ACTIVE
NEGATIVE CAPACITANCE

ABSTRACT

[0043] The present invention is an apparatus and system for reducing bondpad capacitance of an integrated circuit. Circuitry of the present invention may produce a negative capacitance approximately equal in magnitude to the capacitance associated with the bondpad and thereby effectively eliminate the bondpad capacitance. Values of the components of the circuitry may be selectively and independently chosen to synthesize a variable range of negative capacitance and thus produce a negative capacitance approximately equal in magnitude to a unique capacitance associated with the bondpad of a variety of integrated circuits.